

General Description

The MAX536/MAX537 combine four 12-bit, voltage-output digital-to-analog converters (DACs) and four precision output amplifiers in a space-saving 16-pin package. Offset, gain, and linearity are factory calibrated to provide the MAX536's ±1 LSB total unadjusted error. The MAX537 operates with ±5V supplies, while the MAX536 uses -5V and +10.8V to +13.2V supplies.

Each DAC has a double-buffered input, organized as an input register followed by a DAC register. A 16-bit serial word is used to load data into each input/DAC register. The serial interface is compatible with either SPI/QSPI™ or MICROWIRE™, and allows the input and DAC registers to be updated independently or simultaneously with a single software command. The DAC registers can be simultaneously updated with a hardware LDAC pin. All logic inputs are TTL/CMOS compatible.

Applications

Industrial Process Controls

Automatic Test Equipment

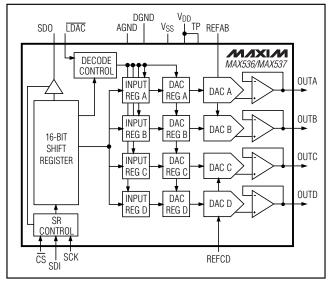
Digital Offset and Gain Adjustment

Motion Control Devices

Remote Industrial Controls

Microprocessor-Controlled Systems

Functional Diagram



Features

- ♦ Four 12-Bit DACs with Output Buffers
- Simultaneous or Independent Control of Four **DACs via a 3-Wire Serial Interface**
- ♦ Power-On Reset
- ♦ SPI/QSPI and MICROWIRE Compatible
- ♦ ±1 LSB Total Unadjusted Error (MAX536)
- **♦ Full 12-Bit Performance without Adjustments**
- **♦** ±5V Supply Operation (MAX537)
- **♦ Double-Buffered Digital Inputs**
- **♦** Buffered Voltage Output
- ♦ 16-Pin DIP/SO Packages

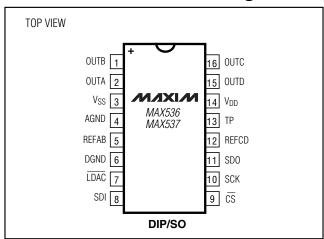
Ordering Information

PART	TEMP RANGE	PIN- PACKAGE	INL (LSB)
MAX536ACPE+	0°C to +70°C	16 PDIP	±0.5
MAX536BCPE+	0°C to +70°C	16 PDIP	±1
MAX536ACWE+	0°C to +70°C	16 Wide SO	±0.5
MAX536BCWE+	0°C to +70°C	16 Wide SO	±1
MAX536AEPE+	-40°C to +85°C	16 PDIP	±0.5
MAX536BEPE+	-40°C to +85°C	16 PDIP	±1
MAX536AEWE+	-40°C to +85°C	16 Wide SO	±0.5
MAX536BEWE+	-40°C to +85°C	16 Wide SO	±1

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

Ordering Information continued at end of data sheet.

Pin Configuration



SPI and QSPI are trademarks of Motorola, Inc. MICROWIRE is a trademark of National Semiconductor Corp.

ABSOLUTE MAXIMUM RATINGS

V _{DD} to AGND or DGND	
MAX536	0.3V to +13.2V
MAX537	0.3V to +7V
Vss to AGND or DGND	7V to +0.3V
SDI, SCK, CS, LDAC, TP, SDO	
to AGND or DGND	$0.3V$ to $(V_{DD} + 0.3V)$
REFAB, REFCD to AGND or DGND	0.3V to $(VDD + 0.3V)$
OUT_ to AGND or DGND	VDD to VSS
Maximum Current into Any Pin	50mA

Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
Plastic DIP (derate 10.53mW/°C above +70°C)	842mW
Wide SO (derate 9.52mW/°C above +70°C).	762mW
Operating Temperature Ranges	
MAX53_AC_E/BC_E	0°C to +70°C
MAX53_AE_E/BE_E	40°C to +85°C
Storage Temperature Range	
Lead Temperature (soldering, 10s)	
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—MAX536

 $(V_{DD} = +12V, V_{SS} = -5V, REFAB/REFCD = 8V, AGND = DGND = 0V, R_L = 5k\Omega, C_L = 100pF, T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted. Typical values are at $T_A = +25$ °C.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS			
STATIC PERFORMANCE—ANALOG SECTION										
Resolution	N			12			Bits			
		T 050C	MAX536A			±1.0				
		$T_A = +25^{\circ}C$	MAX536B			±2.0				
Total Upadiustad Error (Note 1)	TUE		MAX536AC			±2.0	LSB			
Total Unadjusted Error (Note 1)	TUE	T. T to T	MAX536BC			±3.0	LSB			
		$T_A = T_{MIN}$ to T_{MAX}	MAX536AE			±2.5				
			MAX536BE			±3.5				
Integral Newline exity	INII	MAX536A			±0.15	±0.50	1.00			
Integral Nonlinearity	INL	MAX536B				±1	LSB			
Differential Nonlinearity	DNL	Guaranteed monotonic				±1	LSB			
		MAX536A				±2.5				
		$T_A = +25^{\circ}C$	MAX536B			±5.0]			
044 5			MAX536AC			±5.0				
Offset Error			MAX536BC			±7.5	mV			
		$T_A = T_{MIN}$ to T_{MAX}	MAX536AE			±6.1				
			MAX536BE			±8.5				
		R _L = ∞			-0.1	±1.0				
Gain Error		D. ELO	MAX536_C/E		-0.6	±1.5	LSB			
		$R_L = 5k\Omega$ MAX536_M				±2.0				
V _{DD} Power-Supply Rejection Ratio	PSRR	T _A = +25°C, 10.8V < V _{DD} < 13.2V			±0.02	±0.125	LSB/V			
V _{SS} Power-Supply Rejection Ratio	PSRR	$T_A = +25^{\circ}C$, -5.5V < V_{DD} < -4.5V ± 0.03 ± 0.3				±0.30	LSB/V			

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ELECTRICAL CHARACTERISTICS—MAX536 (continued)

 $(V_{DD}=+12V,\,V_{SS}=-5V,\,REFAB/REFCD=8V,\,AGND=DGND=0V,\,R_L=5k\Omega,\,C_L=100pF,\,T_A=T_{MIN}\,to\,T_{MAX},\,unless\,otherwise\,noted.\,Typical\,values\,are\,at\,T_A=+25^{\circ}C.)$

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
MATCHING PERFORMANCE (T	_A = +25°C)						
T	TUE	MAX536A				±1.0	1.00
Total Unadjusted Error	TUE	MAX536B				±2.0	LSB
Gain Error					±0.1	±1.0	LSB
Officet Francis		MAX536A			±1.2	±2.5	\/
Offset Error		MAX536B			±1.2	±5.0	mV
Integral Nonlinearity	INL				±0.2	±1.0	LSB
REFERENCE INPUT							
Reference Input Range	REF			0		V _{DD} - 4	V
Reference Input Resistance	R _{REF}	Code depender	nt, minimum at code 555	5			kΩ
MULTIPLYING-MODE PERFORI	MANCE			•			
Reference 3dB Bandwidth		V _{REF} = 2V _{P-P}			700		kHz
D. (Input code =	V _{REF} = 10V _{P-P} at 400Hz		-100		- 5
Reference Feedthrough		all 0s	VREF = 10Vp-p at 4kHz		-82		dB
Total Harmonic Distortion Plus Noise	THD+N	V _{REF} = 2.0V _{P-P}			0.024		%
DIGITAL INPUTS (SDI, SCK, CS	LDAC)	l		l			ı
Input High Voltage	V _{IH}			2.4			V
Input Low Voltage	VIL					0.8	V
Input Leakage Current		V _{IN} = 0V or V _{DD})			1.0	μΑ
Input Capacitance (Note 2)		1111				10	pF
DIGITAL OUTPUT (SDO)		<u> </u>					1 1-
Output Low Voltage	VoL	SDO sinking 5m	ıA		0.13	0.40	V
Output Leakage Current	02	SDO = $0V \text{ to } V_D$				±10	μΑ
DYNAMIC PERFORMANCE (RL	= $5k\Omega$, C_1 =			I			
Voltage Output Slew Rate	T				5		V/µs
Output Settling Time		To ±0.5 LSB of	full scale		3		μs
Digital Feedthrough					5		nV-s
Digital Crosstalk (Note 3)		V _{REF} = 5V			8		nV-s
POWER SUPPLIES		l		I.			I
Positive Supply Range	V_{DD}			10.8		13.2	V
Negative Supply Range	Vss			-4.5		-5.5	V
Positive Supply Current		T _A = +25°C			8	18	
(Note 4)	IDD	$T_A = T_{MIN}$ to T_{MIN}	AX			25	mA
Negative Supply Current		T _A = +25°C			-6	-16	
(Note 4)	ISS	$T_A = T_{MIN}$ to T_{MIN}	AX			-23	mA

ELECTRICAL CHARACTERISTICS—MAX536 (continued)

 $(V_{DD} = +12V, V_{SS} = -5V, REFAB/REFCD = 8V, AGND = DGND = 0V, R_L = 5k\Omega, C_L = 100pF, T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted. Typical values are at $T_A = +25$ °C.)

PARAMETER	SYMBOL	CONDIT	MIN	TYP	MAX	UNITS	
TIMING CHARACTERISTIC	CS (Note 5)			<u>.</u>			•
Internal Power-On Reset Pulse Width (Note 2)	tpor					20	μs
SCK Clock Period	tcp			100			ns
SCK Pulse Width High	tсн			30			ns
SCK Pulse Width Low	tcL			30			ns
CS Fall to SCK Rise Setup Time	tcss			20			ns
SCK Rise to CS Rise Hold Time	tcsh			10			ns
SDI Setup Time	tDS			40	26		ns
SDI Hold Time	tDH			0			ns
SCK Rise to SDO Valid	tDO1	1 k Ω pullup on SDO	SDO high		78	105	ns
Propagation Delay (Note 6)	וטטו	to VDD, C _{LOAD} = 50pF	SDO low		50	80	113
SCK Fall to SDO Valid	tDO2	1k Ω pullup on SDO	SDO high		81	110	ns
Propagation Delay (Note 7)	1002	to V _{DD} , C _{LOAD} = 50pF	SDO low		53	85	113
CS Fall to SDO Enable (Note 8)	t _{DV}				27	45	ns
CS Rise to SDO Disable (Note 9)	tTR				40	60	ns
SCK Rise to CS Fall Delay	tcso	Continuous SCK, SCK edge	20			ns	
CS Rise to SCK Rise Hold Time	tCS1	SCK edge ignored	20			ns	
LDAC Pulse Width Low	tLDAC			30			ns
CS Pulse Width High	tcsw			40			ns

- Note 1: TUE is specified with no resistive load.
- Note 2: Guaranteed by design.
- Note 3: Crosstalk is defined as the glitch energy at any DAC output in response to a full-scale step change on any other DAC.
- Note 4: Digital inputs at 2.4V; with digital inputs at CMOS levels, IDD decreases slightly.
- **Note 5:** All input signals are specified with $t_R = t_F \le 5$ ns. Logic input swing is 0 to 5V.
- Note 6: Serial data clocked out of SDO on SCK's falling edge. (SDO is an open-drain output for the MAX536. The MAX537's SDO pin has an internal active pullup.)
- Note 7: Serial data clocked out of SDO on SCK's rising edge.
- Note 8: SDO changes from High-Z state to 90% of final value.
- Note 9: SDO rises 10% toward High-Z state.

ELECTRICAL CHARACTERISTICS—MAX537

 $(V_{DD}=+5V,\,V_{SS}=-5V,\,REFAB/REFCD=2.5V,\,AGND=DGND=0V,\,R_L=5k\Omega,\,C_L=100pF,\,T_A=T_{MIN}$ to $T_{MAX},\,unless$ otherwise noted. Typical values are at $T_A=+25^{\circ}C.)$

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
STATIC PERFORMANCE—ANAL	OG SECTIO	N					
Resolution	N			12			Bits
Integral Newline exity	INII	MAX537A			±0.15	±0.50	LOD
Integral Nonlinearity	INL	MAX537B				±1	LSB
Differential Nonlinearity	DNL	Guaranteed monoton	ic			±1	LSB
		T _A = +25°C	MAX537A			±3.0	
		1A = +25 C	MAX537B			±6.0	
Offset Error			MAX537AC			±6.0	m\/
Oliset Error		T. T to T	MAX537BC			±9.0	mV
		$T_A = T_{MIN}$ to T_{MAX}	MAX537AE			±7.0	
			MAX537BE			±11.0	
Gain Error		R _L = ∞			-0.3	±1.5	LSB
Gain Enoi		$R_L = 5k\Omega$			-0.8	±3.0	LOD
V _{DD} Power-Supply Rejection Ratio	PSRR	T _A = +25°C, 4.5V ≤ V	_{DD} ≤ 5.5V		±0.01	±0.5	LSB/V
V _{SS} Power-Supply Rejection Ratio	PSRR	$T_A = +25^{\circ}C, -5.5V \le V$	V _{SS} ≤ -4.5V		±0.02	±0.7	LSB/V
MATCHING PERFORMANCE (TA	= +25°C)						
Gain Error					±0.1	±1.25	LSB
Offset Error		MAX537A			±0.3	±3.0	mV
Oliset Elfor		MAX537B			±0.3	±6.0	IIIV
Integral Nonlinearity	INL				±0.35	±1.0	LSB
REFERENCE INPUT							
Reference Input Range	REF			0		V _{DD} - 2.2	V
Reference Input Resistance	RREF	Code dependent, mir	nimum at code 555 hex	5			kΩ
MULTIPLYING-MODE PERFORM	ANCE						
Reference 3dB Bandwidth		V _{REF} = 2V _{P-P}			700		kHz
5			V _{REF} = 10V _{P-P} at 400Hz		-100		15
Reference Feedthrough		Input code = all 0s	V _{REF} = 10V _{P-P} at 4kHz		-82		dB
Total Harmonic Distortion Plus Noise	THD+N	$V_{REF} = 850 \text{mVp-p} \text{ at } 100 \text{kHz}$			0.024		%
DIGITAL INPUTS (SDI, SCK, CS,	LDAC)						
Input High Voltage	ViH			2.4			V
Input Low Voltage	V _{IL}					0.8	V
Input Leakage Current		V _{IN} = 0V or V _{DD}				1.0	μΑ
Input Capacitance (Note 2)						10	pF
	1	i		1			

ELECTRICAL CHARACTERISTICS—MAX537 (continued)

 $(V_{DD} = +5V, V_{SS} = -5V, REFAB/REFCD = 2.5V, AGND = DGND = 0V, R_L = 5k\Omega, C_L = 100pF, T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted. Typical values are at $T_A = +25$ °C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DIGITAL OUTPUT (SDO)						
Output High Voltage	VoH	SDO sourcing 2mA	V _{DD} - 0.5	V _{DD} - 0.25		V
Output Low Voltage	V _{OL}	SDO sinking 2mA		0.13	0.40	V
DYNAMIC PERFORMANCE (RL =	5kΩ, CL =	100pF)				
Voltage Output Slew Rate				5		V/µs
Output Settling Time		To ±0.5 LSB of full scale		5		μs
Digital Feedthrough				5		nV-s
Digital Crosstalk (Note 3)				5		nV-s
POWER SUPPLIES						
Positive Supply Range	V_{DD}		4.5		5.5	V
Negative Supply Range	V _{SS}		-4.5		-5.5	V
Positive Supply Current (Note 4)	loo	T _A = +25°C		5.5	12	mA
rositive Supply Current (Note 4)	I _{DD}	$T_A = T_{MIN}$ to T_{MAX}			16	IIIA
Negative Supply Current (Note 4)	I _{SS}	T _A = +25°C		-4.7	-10	mA
Negative Supply Current (Note 4)	155	$T_A = T_{MIN}$ to T_{MAX}				IIIA
TIMING CHARACTERISTICS (Not	e 5)					
Internal Power-On Reset Pulse Width (Note 2)	tpor				50	μs
SCK Clock Period	tCP		100			ns
SCK Pulse Width High	tсн	MAX537_C/E	35			ns
SCK Pulse Width Low	tCL	MAX537_C/E	35			ns
CS Fall to SCK Rise Setup Time	tcss	MAX537_C/E	40			ns
SCK Rise to CS Rise Hold Time	tcsh		0			ns
SDI Setup Time	tDS	MAX537_C/E	40	24		ns
SDI Hold Time	tDH		0			ns
SCK Rise to SDO Valid		CLOAD = 500E MAY537 C/E		116	200	ne
Propagation Delay (Note 6)	t _{DO1}	C _{LOAD} = 50pF, MAX537_C/E		1 10	200	ns
SCK Fall To SDO Valid Propagation Delay (Note 7)	t _{DO2}	C _{LOAD} = 50pF, MAX537_C/E		123	210	ns

ELECTRICAL CHARACTERISTICS—MAX537 (continued)

 $(V_{DD} = +5V, V_{SS} = -5V, REFAB/REFCD = 2.5V, AGND = DGND = 0V, R_L = 5k\Omega, C_L = 100pF, T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted. Typical values are at $T_A = +25$ °C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
CS Fall to SDO Enable	t _{DV}	C _{LOAD} = 50pF, MAX537_C/E		75	140	ns
CS Rise to DSO Disable (Note 10)	t _{TR}	C _{LOAD} = 50pF, MAX537_C/E		70	130	ns
SCK Rise to CS Fall Delay	tcso	Continuous SCK, SCK edge ignored	35			ns
CS Rise to SCK Rise Hold Time	tcs1	SCK edge ignored, MAX537_C/E	35			ns
LDAC Pulse Width High	tLDAC	MAX537_C/E	50			ns
CS Pulse Width High	tcsw	MAX537_C/E	100		·	ns

Note 2: Guaranteed by design.

Note 3: Crosstalk is defined as the glitch energy at any DAC output in response to a full-scale step change on any other DAC.

Note 4: Digital inputs at 2.4V; with digital inputs at CMOS levels, IDD decreases slightly.

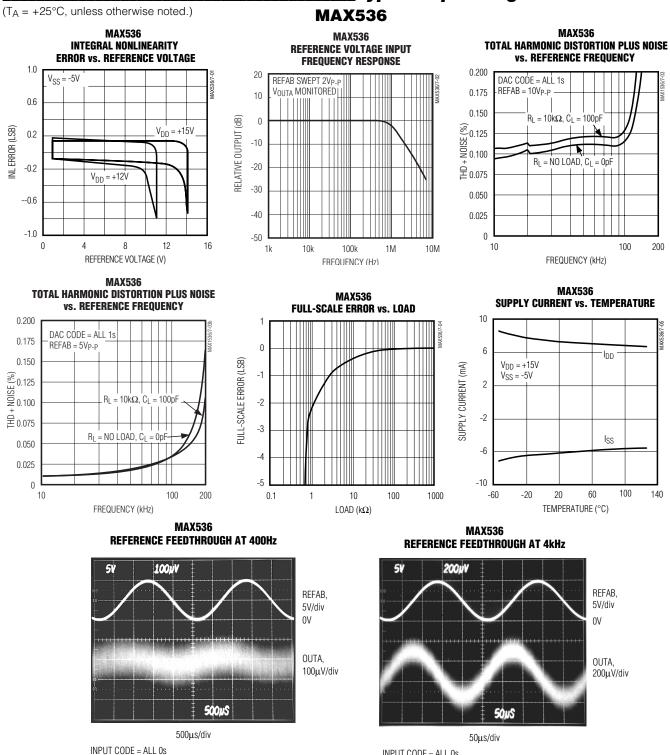
Note 5: All input signals are specified with $t_R = t_F \le 5$ ns. Logic input swing is 0 to 5V.

Note 6: Serial data clocked out of SDO on SCK's falling edge. (SDO is an open-drain output for the MAX536. The MAX537's SDO pin has an internal active pullup.)

Note 7: Serial data clocked out of SDO on SCK's rising edge.

Note 10: When disabled, SDO is internally pulled high.

Typical Operating Characteristics



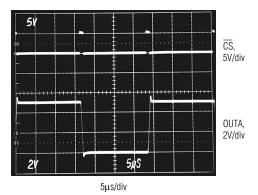
INPUT CODE = ALL 0s

Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$

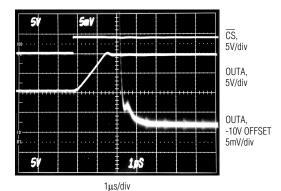
MAX536

MAX536 Dynamic response (all bits on, off, on)



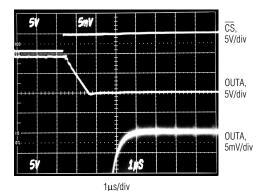
 V_{DD} = +15V, V_{SS} = -5V, REFAB = 5V, C_L = 100pF, R_L = 10k Ω

MAX536 POSITIVE FULL-SCALE SETTLING TIME (ALL BITS OFF TO ALL BITS ON)



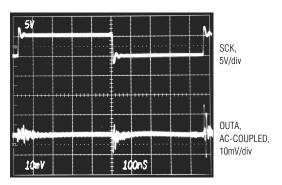
 V_{DD} = +15V, V_{SS} = -5V, REFAB = 10V, C_L = 100pF, R_L = 10k Ω

MAX536 NEGATIVE FULL-SCALE SETTLING TIME (ALL BITS ON TO ALL BITS OFF)



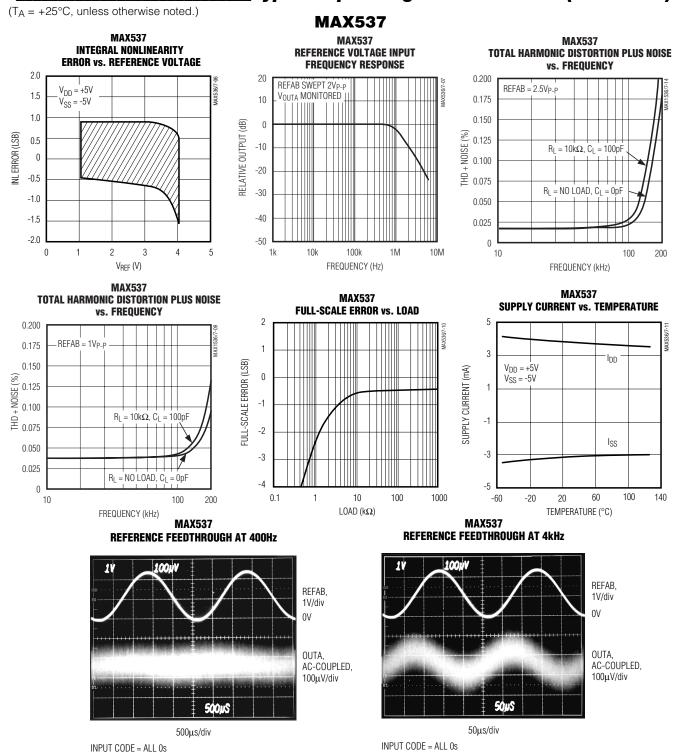
 $V_{DD} = +15V$, $V_{SS} = -5V$, REFAB = 10V, $C_1 = 100$ pF, $R_1 = 10$ k Ω

MAX536 DIGITAL FEEDTHROUGH



 $\rm V_{DD}$ = +15V, $\rm V_{SS}$ = -5V, REFAB = 10V, $\overline{\rm CS}$ = HIGH, DIN TOGGLING AT $1\!\!\!/_2$ THE CLOCK RATE, OUTA = 5V

Typical Operating Characteristics (continued)

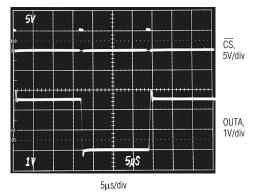


_Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$

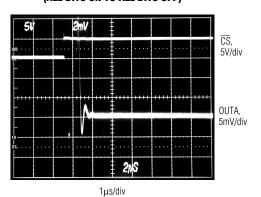
MAX537

MAX537 DYNAMIC RESPONSE (ALL BITS ON, OFF, ON)



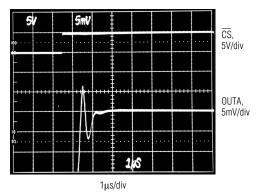
 V_{DD} = +5V, V_{SS} = -5V, REFAB = 2.5V, C_{I} = 100pF, R_{I} = 10k Ω

MAX537 NEGATIVE FULL-SCALE SETTLING TIME (ALL BITS ON TO ALL BITS OFF)



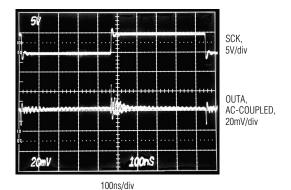
 V_{DD} = +5V, V_{SS} = -5V, REFAB = 2.5V, C_L = 100pF, R_L = 10k Ω

MAX537 POSITIVE FULL-SCALE SETTLING TIME (ALL BITS OFF TO ALL BITS ON)



 V_{DD} = +5V, V_{SS} = -5V, REFAB = 2.5V, C_{L} = 100pF, R_{L} = 10k Ω

MAX537 DIGITAL FEEDTHROUGH



 $\rm V_{DD}$ = +5V, V_{SS} = -5V, REFAB = 2.5V, $\overline{\rm CS}$ = HIGH, DIN TOGGLING AT $1\!\!/_2$ THE CLOCK RATE, OUTA = 1.25V

Pin Description

PIN	NAME	FUNCTION
1	OUTB	DAC B Output Voltage
2	OUTA	DAC A Output Voltage
3	V _{SS}	Negative Power Supply
4	AGND	Analog Ground
5	REFAB	Reference Voltage Input for DAC A and DAC B
6	DGND	Digital Ground
7	LDAC	Load DAC Input (active low). Driving this asynchronous input low transfers the contents of all input registers to their respective DAC registers.
8	SDI	Serial Data Input. Data is shifted into an internal 16-bit shift register on SCK's rising edge.
9	CS	Chip-Select Input (active low). A low level on $\overline{\text{CS}}$ enables the input shift register and SDO. On $\overline{\text{CS}}$'s rising edge, data is latched into the appropriate register(s).
10	SCK	Shift Register Clock Input
11	SDO	Serial Data Output. SDO is the output of the internal shift register. SDO is enabled when $\overline{\text{CS}}$ is low. For the MAX536, SDO is an open-drain output. For the MAX537, SDO has an active pullup to V_{DD} .
12	REFCD	Reference Voltage Input for DAC C and DAC D
13	TP	Test Pin. Connect to V _{DD} for proper operation.
14	V _{DD}	Positive Power Supply
15	OUTD	DAC D Output Voltage
16	OUTC	DAC C Output Voltage

Detailed Description

The MAX536/MAX537 contain four 12-bit voltage-output DACs that are easily addressed using a simple 3-wire serial interface. They include a 16-bit data-in/data-out shift register, and each DAC has a double-buffered input composed of an input register and a DAC register (see the *Functional Diagram* on the front page).

The DACs are "inverted" R-2R ladder networks that convert 12-bit digital inputs into equivalent analog output voltages in proportion to the applied reference-voltage inputs. DAC A and DAC B share the REFAB reference input, while DAC C and DAC D share the REFCD reference input. The two reference inputs allow different full-scale output voltage ranges for each pair of DACs. Figure 1 shows a simplified circuit diagram of one of the four DACs.

Reference Inputs

The two reference inputs accept positive DC and AC signals. The voltage at each reference input sets the full-scale output voltage for its two corresponding DACs. The REFAB/REFCD voltage range is 0V to (VDD - 4V) for the MAX536 and 0V to (VDD - 2.2V) for the MAX537. The output voltages VOUT_ are represented by

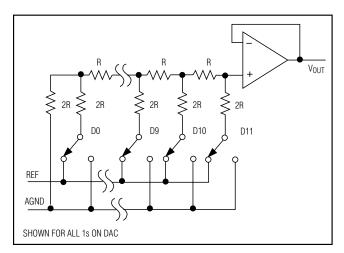


Figure 1. Simplified DAC Circuit Diagram

a digitally programmable voltage source as:

$$V_{OUT} = N_B (V_{REF})/4096$$

where NB is the numeric value of the DAC's binary input code (0 to 4095) and V_{REF} is the reference voltage.

__ //IXI/N

The input impedance at each reference input is code dependent, ranging from a low value of typically $6k\Omega$ (with an input code of 0101 0101 0101) to a high value of $60k\Omega$ (with an input code of 0000 0000 0000). Since the input impedance at the reference pins is code dependent, load regulation of the reference source is important.

The REFAB and REFCD reference inputs have a $5k\Omega$ guaranteed minimum input impedance. When the two reference inputs are driven from the same source, the effective minimum impedance becomes $2.5k\Omega$.

The reference input capacitance is also code dependent and typically ranges from 125pF to 300pF.

Output Buffer Amplifiers

All MAX536/MAX537 voltage outputs are internally buffered by precision unity-gain followers with a typical slew rate of 5V/ μ s for the MAX536 and 3V/ μ s for the MAX537.

With a full-scale transition at the MAX536 output (0 to 8V or 8V to 0), the typical settling time to ± 0.5 LSB is $3\mu s$ when loaded with $5k\Omega$ in parallel with 100pF (loads less than $5k\Omega$ degrade performance).

With a full-scale transition at the MAX537 output (0 to 2.5V or 2.5V to 0), the typical settling time to ± 0.5 LSB

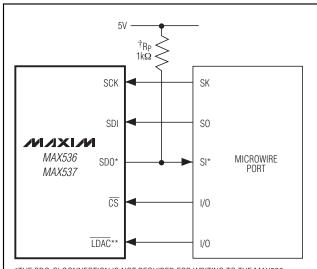
is $5\mu s$ when loaded with $5k\Omega$ in parallel with 100pF (loads less than $5k\Omega$ degrade performance).

Output dynamic responses and settling performances of the MAX536/MAX537 output amplifier are shown in the *Typical Operating Characteristics*.

Serial-Interface Configurations

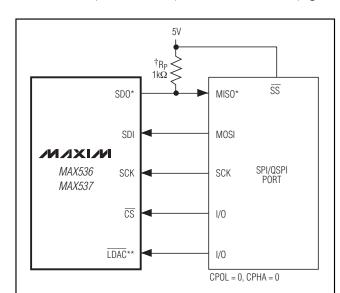
The MAX536/MAX537's 3-wire or 4-wire serial interface is compatible with both MICROWIRE (Figure 2) and SPI/QSPI (Figure 3). In Figures 2 and 3, LDAC can be tied either high or low for a 3-wire interface, or used as the fourth input with a 4-wire interface. The connection between SDO and the serial-interface port is not necessary, but may be used for data echo. (Data held in the shift register of the MAX536/MAX537 can be shifted out of SDO and returned to the microprocessor for data verification; data in the MAX536/MAX537 input/DAC registers cannot be read.)

With a 3-wire interface ($\overline{\text{CS}}$, SCK, SDI) and $\overline{\text{LDAC}}$ tied high, the DACs are double-buffered. In this mode, depending on the command issued through the serial interface, the input register(s) may be loaded without affecting the DAC register(s), the DAC register(s) can be loaded directly, or all four DAC registers may be simultaneously updated from the input registers. With a 3-wire interface ($\overline{\text{CS}}$, SCK, SDI) and $\overline{\text{LDAC}}$ tied low (Figure



*THE SDO-SI CONNECTION IS NOT REQUIRED FOR WRITING TO THE MAX536, BUT MAY BE USED FOR READBACK PURPOSES.

Figure 2. Connections for MICROWIRE



*THE SDO-MISO CONNECTION IS NOT REQUIRED FOR WRITING TO THE MAX536, BUT MAY BE USED FOR READBACK PURPOSES.

Figure 3. Connections for SPI/QSPI



^{**}THE LDAC CONNECTION IS NOT REQUIRED WHEN USING THE 3-WIRE INTERFACE.

[†]THE MAX537 HAS AN INTERNAL ACTIVE PULLUP TO $V_{DD,}$ SO R_P IS NOT NECESSARY.

^{**}THE LDAC CONNECTION IS NOT REQUIRED WHEN USING THE 3-WIRE INTERFACE.

 $^{^{\}dagger}$ THE MAX537 HAS AN INTERNAL ACTIVE PULLUP TO V_{DD} , SO R_P IS NOT NECESSARY.

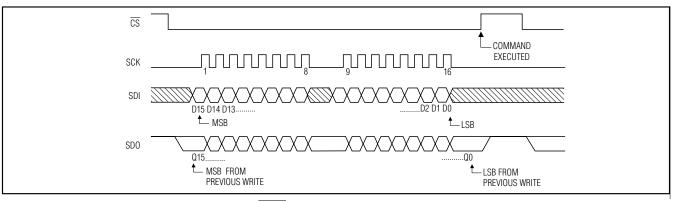


Figure 4. 3-Wire Serial-Interface Timing Diagram ($\overline{LDAC} = GND$ or V_{DD})

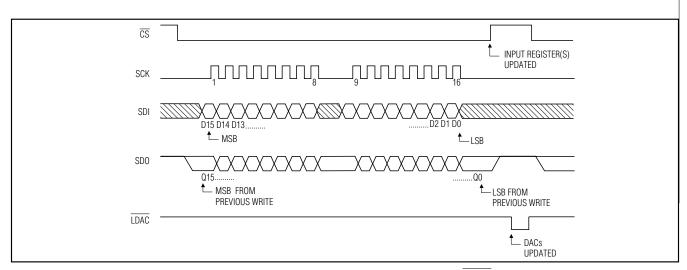


Figure 5. 4-Wire Serial-Interface Timing Diagram for Asynchronous DAC Updating Using LDAC

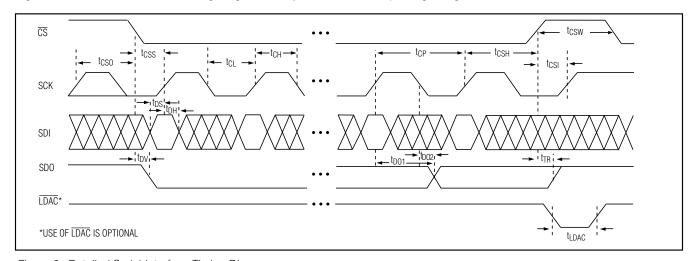


Figure 6. Detailed Serial-Interface Timing Diagram

4), the DAC registers remain transparent. Any time an input register is updated, the change appears at the DAC output with the rising edge of $\overline{\text{CS}}$.

The 4-wire interface (\overline{CS} , SCK, SDI, \overline{LDAC}) is similar to the 3-wire interface with \overline{LDAC} tied high, except \overline{LDAC} is a hardware input that simultaneously and asynchronously loads all DAC registers from their respective input registers when driven low (Figure 5).

Serial-Interface Description

The MAX536/MAX537 require 16 bits of serial data. Data is sent MSB first and can be sent in two 8-bit packets or one 16-bit word ($\overline{\text{CS}}$ must remain low until 16 bits are transferred). The serial data is composed of two DAC address bits (A1, A0), two control bits (C1, C0), and the 12 data bits D11...D0 (Figure 7). The 4-bit address/control code determines the following: 1) the register(s) to be updated and/or the status of the input and DAC registers (i.e., whether they are in transparent or latch mode), and 2) the edge on which data is clocked out of SDO.

Figure 6 shows the serial-interface timing requirements. The chip-select pin $\overline{(CS)}$ must be low to enable the DAC's serial interface. When \overline{CS} is high, the interface control circuitry is disabled and the serial data output pin (SDO) is driven high (MAX537) or is a high-impedance open drain (MAX536). \overline{CS} must go low at least t_{CSS} before the rising serial clock (SCK) edge to properly clock in the first bit. When \overline{CS} is low, data is clocked into the internal shift register via the serial data input pin (SDI) on SCK's rising edge. The maximum guaranteed clock frequency is 10MHz. Data is latched into the appropriate MAX536/MAX537 input/DAC registers on \overline{CS} 's rising edge.

MSE	MSBLSB									
←	← 16 Bits of Serial Data ←									
	ress ts	Control Bits		Data Bits MSBL	SB					
A1	A0	C1	C0	D11	D0					
←	4 Add Contr	dress/. ol Bits	-	12 Data Bits	\					

Figure 7. Serial-Data Format (MSB Sent First)

Interface timing is optimized when serial data is clocked out of the microcontroller/microprocessor on one clock edge and clocked into the MAX536/MAX537 on the other edge. Table 1 lists the serial-interface programming commands. For certain commands, the 12 data bits are "don't cares".

The programming command Load-All-DACs-From-Shift-Register allows all input and DAC registers to be simultaneously loaded with the same digital code from the input shift register. The NOP (no operation) command allows the register contents to be unaffected and is useful when the MAX536/MAX537 are configured in a daisy-chain (see the Daisy-Chaining Devices section). The command to change the clock edge on which serial data is shifted out of the MAX536/MAX537 SDO pin also loads data from all input registers to their respective DAC registers.

Serial-Data Output

The serial-data output, SDO, is the internal shift register's output. The MAX536/MAX537 can be programmed so that data is clocked out of SDO on SCK's rising (Mode 1) or falling (Mode 0) edge . In Mode 0, output data at SDO lags input data at SDI by 16.5 clock cycles, maintaining compatibility with MICROWIRE, SPI/QSPI, and other serial interfaces. In Mode 1, output data lags input data by 16 clock cycles. On power-up, SDO defaults to Mode 1 timing.

For the MAX536, SDO is an open-drain output that should be pulled up to +5V. The data sheet timing specifications for SDO use a 1k Ω pullup resistor. For the MAX537, SDO is a complementary output and does not require an external pullup.

Test Pin

The test pin (TP) is used for pre-production analysis of the IC. Connect TP to Vpp for proper MAX536/MAX537 operation. Failure to do so affects DAC operation.

Daisy-Chaining Devices

Any number of MAX536/MAX537s can be daisy-chained by connecting the SDO pin of one device (with a pullup resistor, if appropriate) to the SDI pin of the following device in the chain (Figure 8).

Since the MAX537's SDO pin has an internal active pullup, the SDO sink/source capability determines the time required to discharge/charge a capacitive load. Refer to the serial data out V_{OH} and V_{OL} specifications in the *Electrical Characteristics*.

Table 1. Serial-Interface Programming Commands

	16-BIT SERIAL WORD		LDAC	FUNCTION		
A1	Α0	C1	C0	D11D0	LDAC	FONCTION
0	0	0	1	12-bit DAC data	1	Load DAC A input register; DAC output unchanged.
0	1	0	1	12-bit DAC data	1	Load DAC B input register; DAC output unchanged.
1	0	0	1	12-bit DAC data	1	Load DAC C input register; DAC output unchanged.
1	1	0	1	12-bit DAC data	1	Load DAC D input register; DAC output unchanged.
0	0	1	1	12-bit DAC data	1	Load input register A; all DAC registers updated.
0	1	1	1	12-bit DAC data	1	Load input register B; all DAC registers updated.
1	0	1	1	12-bit DAC data	1	Load input register C; all DAC registers updated.
1	1	1	1	12-bit DAC data	1	Load input register D; all DAC registers updated.
Х	0	0	0	12-bit DAC data	Х	Load all DACs from shift register.
X	1	0	0	XXXXXXXXXX	Х	No operation (NOP)
0	Χ	1	0	XXXXXXXXXXX	1	Update all DACs from their respective input registers.
1	1	1	0	xxxxxxxxxx	X	Mode 1 (default condition at power-up), DOUT clocked out on SCK's rising edge. All DACs updated from their respective input registers.
1	0	1	0	xxxxxxxxxx	X	Mode 0, DOUT clocked out on SCK's falling edge. All DACs updated from their respective input registers.
0	0	Х	1	12-bit DAC data	0	Load DAC A input register; DAC A is immediately updated.
0	1	Х	1	12-bit DAC data	0	Load DAC B input register; DAC B is immediately updated.
1	0	X	1	12-bit DAC data	0	Load DAC C input register; DAC C is immediately updated.
1	1	X	1	12-bit DAC data	0	Load DAC D input register; DAC D is immediately updated.

[&]quot;X" = Don't Care. $\overline{\text{LDAC}}$ provides true latch control: when $\overline{\text{LDAC}}$ is low, the DAC registers are transparent; when $\overline{\text{LDAC}}$ is high, the DAC registers are latched.

When daisy-chaining MAX536s, the delay from $\overline{\text{CS}}$ low to SCK high (tcss) must be the greater of:

$$tDV + tDS$$
 or $tTR + tRC + tDS - tCSW$

where t_{RC} is the time constant of the external pullup resistor (R_p) and the load capacitance (C) at SDO. For t_{RC} < 20ns, t_{CSS} is simply t_{DV} + t_{DS} . Calculate t_{RC} from the following equation:

$$t_{RC} = R_p(C) \left[ln \left(\frac{V_{PULLUP}}{V_{PULLUP} - 2.4V} \right) \right]$$

where VPULLUP is the voltage to which the pullup resistor is connected.

Additionally, when daisy-chaining devices, the maximum clock frequency is limited to:

$$f_{SCK}(max) = \frac{1}{2(t_{DO} + t_{RC} - 38ns + t_{DS})}$$

For example, with tRC = 23ns (5V $\pm 10\%$ supply with Rp = 1k Ω and C = 30pF), the maximum clock frequency is 8.7MHz.

Figure 9 shows an alternate method of connecting several MAX536/MAX537s. In this configuration, the data bus is common to all devices; data is not shifted through a daisy-chain. More I/O lines are required in this configuration because a dedicated chip-select input (CS) is required for each IC.

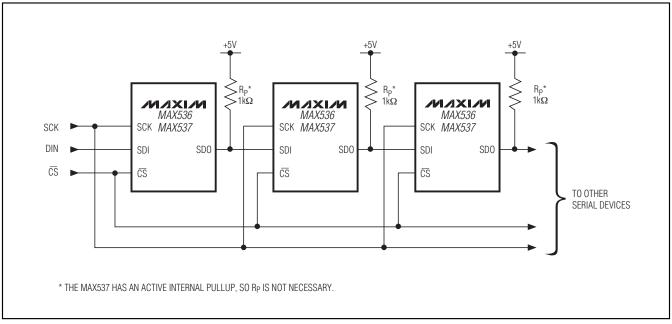


Figure 8. Daisy-Chaining MAX536/MAX537s with a 3-Wire Serial Interface

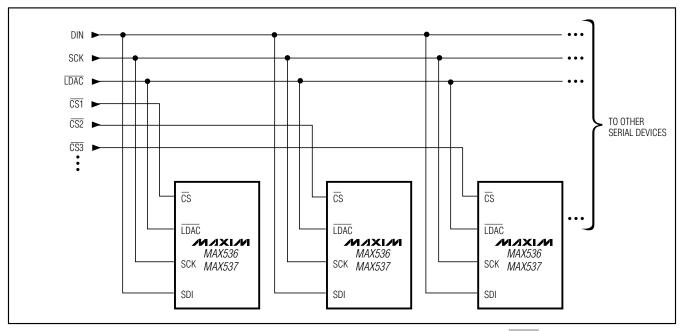


Figure 9. Multiple devices sharing a common DIN line may be simultaneously updated by bringing $\overline{\text{LDAC}}$ low. CS1, CS2, CS3... are driven separately, thus controlling which data are written to devices 1, 2, 3...

_Applications Information Interfacing to the M68HC11*

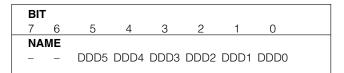
PORT D of the 68HC11 supports SPI. The four registers used for SPI operation are the Serial Peripheral Control Register, the Serial Peripheral Status Register, the Serial Peripheral Data I/O Register, and PORT D's Data Direction Register. These registers have a default starting location of \$1000

On reset, the PORT D register (memory location \$1008) is cleared and bits 5-0 are configured as general-purpose inputs. Setting bit 6 (SPE) of the Serial Peripheral Control Register (SPCR) configures PORT D for SPI as follows:

BIT	•							
7	6	5	4	3	2	1	0	
NA	ME							
-	-	SS	SCK	MOSI	MISO	TXD	RXD	

Bits 6 and 7 are not used. Writes to these bits are ignored.

The PORT D Data Direction Register (DDRD) determines whether the port bits are inputs or outputs. Its configuration is shown below:



Setting DDD_ = 0 configures the port bit as an input, while setting DDD_ = 1 configures the port bit as an output. Writes to bits 6 and 7 have no effect.

In SPI mode with MSTR = 1, when a PORT D bit is expected to be an input (\overline{SS} , MISO, RXD), the corresponding DDRD bit (DDD_) is ignored. If the bit is expected to be an output (SCK, MOSI, TXD), the corresponding DDRD bit must be set for the bit to be an output.

Table 2. Serial Peripheral Control-Register Definitions

NAME	DEFINITION								
SPIE	Serial Peripheral Interrupt Enable. Clearing SPIE disables the SPI hardware-interrupt request; the SPSR is polled to determine when an SPI data transfer is complete. Setting SPIE requests a hardware interrupt when the Serial Peripheral Status Register's SPIF bit or MODF bit is set.								
SPE		Setting SPE (Serial Peripheral System Enable) configures PORT D for SPI. Clearing SPE configures the port as a general-purpose I/O port.							
DWOM	When DWOM is set, the six PORT D outputs are open drain. When DWOM is cleared, the outputs are complementary.								
MSTR	Master/Slave select option								
CPOL	Determines clock polarity. When set, the serial clock idles high while data is not being transferred; when cleared, the clock idles low.								
CPHA	Determine	es the clock	phase.						
	SPI Clock	-Rate Selec	t						
	SPR1	SPR0							
CDD1/0	0	0	μP clock divided by 2						
SPR1/0	0	1	μP clock divided by 4						
	1	0	μP clock divided by 16						
	1	1	μP clock divided by 32						

Table 3. Serial Peripheral Status-Register Definitions

NAME	DEFINITION
SPIF	SPIF is set when an SPI data transfer is complete. It is cleared by reading the SPSR and then accessing the SPDR.
WCOL	The Write Collision flag is set when a write to the SPDR occurs while a data transfer is in progress. It is cleared by reading the SPSR and then accessing the SPDR.
MODF	The Mode Fault flag detects master/slave conflicts in a multimaster environment. It is set when the "master" controller has its SS line (PORT D) pulled low, and cleared by reading the SPSR followed by a write to the SPCR.

^{*}M68HC11 is a Motorola microcontroller. General information about the device was obtained from M68HC11 technical manuals.

Table 4. M68HC11 Programming Code

```
* 68HC11 Programming Code for interfacing to the MAX536/MAX537 DACs.
 Data for the MAX536/MAX537 is stored in memory locations $0100 and $0101.
 Release Date February 24, 1994
* Revision 0
* Technical support provided by Motorola
* Additional assistance provided by Diane Scott
**************************
      68HC11 Code
                                 Instruction
       EQU
            $0000
                        ; Memory location for beginning of program
STRT
REGBLK EQU
            $1000
                        ; Starting address for 68HC11 register block
  The following registers will be addressed relative to the start of the
  register block (REGBLK) using indexed addressing mode.
  The effective address = contents of Index Register X + offset.
PORTD
       EQU
            $08
                        ; PORT D memory location
                        ; PORT D Data Direction Register memory location
DDRD
       EQU
SPCR
       EQU
           $28
                        ; SPCR memory location
SPSR
       EQU
            $29
                        ; SPSR memory location
SPDR
       EQU
            $2A
                        ; SPDR memory location
        Start of main program
       ORG STRT
MAIN
       LDAA #$74
                        ; an arbitrary MAX536/MAX537 DAC code (load input
                        ; register B with 1/4 of full-scale value: all DAC
       STAA $0100
                        ; registers updated) is loaded into data memory
       LDAA #$00
       STAA $0101
                        ; locations $0100 and $0101.
       LDX
            #REGBLK
                        ; load Index Register X with starting address of register block
       LDAA #$38
                        ; SPI outputs (SCK, MOSI, and /SS configured as an output)
                        ; configured by setting the Data Direction Register bits
       STAA DDRD,X
                        ; load data into the Data Direction Register
       LDAA #$2F
                        ; set /SS and MOSI high; set SCK low
                        ; load data into PORTD to set-up SPI control lines
       STAA PORTD,X
                        ; set data for SPCR
       LDAA #$51
                        ; load data into the SPCR
       STAA SPCR,X
       BCLR PORTD, X $20 ; bring /CS low
                     ; load high byte of digital data into Accumulator(A)
       LDAA $0100
                        ; load high byte of MAX536/MAX537 data into SPDR
       STAA SPDR,X
       LDAA SPSR,X
                        ; beginning of loop to poll the SPSR
WAIT1
       BITA #$80
                        ; mask all bits except SPIF (transfer complete) flag
            WAIT1
                        ; branch if SPIF is not set to beginning of loop
       BEQ
       LDAA $0101
                        ; load low byte of digital data into Accumulator(A)
                        ; load low byte of MAX536/MAX537 data into SPDR
            SPDR,X
       STAA
WAIT2
       LDAA SPSR,X
                        ; beginning of loop to poll the SPSR
                        ; mask all bits except SPIF (transfer complete) flag
       BITA #$80
       BEQ
            WAIT2
                        ; branch if SPIF is not set to beginning of loop
       LDAA SPDR,X
       LDAA SPDR,X ; read the SPDR to clear the SPIF bit in the SPSR
BSET PORTD,X $20 ; bring /CS high to latch data into the MAX536/MAX537
* The MAX536/MAX537 is now configured to have V_{OUTB} = V_{REF} (1024/4096)
```

 \overline{SS} is an input intended for use in a multimaster environment. However, \overline{SS} or unused PORT D bit RXD, TXD, or possibly MISO (if DAC readback is not used) should be configured as a general-purpose output and used as \overline{CS} by setting the appropriate Data Direction Register bit.

The SPCR configuration (memory location \$1028) is shown below:

BIT 7	6	5	4	3	2	1	0	
NAI SPIE		DWOM	MSTR	CPOL	СРНА	SPR1	SPR0	
SE 1	O	O O	R RESE	ET 0	1	U*	U*	
SE 1	TTING 1	FOR T	YPICA	L SPI (COMMU 0	INICAT	TON 1**	

^{*}U = Unknown

Always configure the 68HC11 as the "master" controller and the MAX536/MAX537 as the "slave" device.

When MSTR = 1 in the SPCR, a write to the Serial Peripheral Data I/O Register (SPDR), located at memory location \$102A, initiates the transmission/reception of data. The data transfer is monitored and the appropriate flags are set in the Serial Peripheral Status Register (SPSR).

The SPSR configuration is shown below:

BIT								
7	6	5	4	3	2	1	0	
NAN SPIF	IE WCOL	_	MODF	_	_	_	_	
RESET CONDITIONS								
0	0	0	0	0	0	0	0	

An example of 68HC11 programming code for a two-byte SPI transfer to the MAX536/MAX537 is given in Table 4. \overline{SS} is used for \overline{CS} , the high byte of MAX536/MAX537 digital data is stored in memory location \$0100, and the low byte is stored in memory location \$0101.

Interfacing to Other Controllers

When using MICROWIRE, refer to the section on *Interfacing to the M68HC11* for guidance, since MICROWIRE can be considered similar to SPI when CPOL = 0 and CPHA = 0. When interfacing to Intel's 80C51/80C31 microcontroller family, use bit-pushing to configure a desired port as the MAX536/MAX537 interface port. Bit-pushing involves arbitrarily assigning I/O port bits as interface control lines, and then writing to the port each time a signal transition is required.

Unipolar Output

For a unipolar output, the output voltages and the reference inputs are the same polarity. Figure 10 shows the MAX536/MAX537 unipolar output circuit, which is also the typical operating circuit. Table 5 lists the unipolar output codes.

Bipolar Output

The MAX536/MAX537 outputs can be configured for bipolar operation using Figure 11's circuit. One op amp and two resistors are required per DAC. With R1 = R2:

$$VOUT = VREF [(2NB/4096) - 1]$$

where N_B is the numeric value of the DAC's binary input code. Table 6 shows digital codes and corresponding output voltages for Figure 11's circuit.

Table 5. Unipolar Code Table

DAC MSB	CONTEN	ITS LSB	ANALOG OUTPUT
1111	1111	1111	+V _{REF} ($\frac{4095}{4096}$)
1000	0000	0001	+V _{REF} (<u>2049</u>)
1000	0000	0000	$+V_{REF}(\frac{2048}{4096}) = \frac{+V_{REF}}{2}$
0111	1111	1111	+V _{REF} ($\frac{2047}{4096}$)
0000	0000	0001	$+V_{REF}(\frac{1}{4096})$
0000	0000	0000	OV

Table 6. Bipolar Code Table

DAC MSB	CONTEN	ITS LSB	ANALOG OUTPUT
1111	1111	1111	+V _{REF} ($\frac{2047}{2048}$)
1000	0000	0001	$+V_{REF}(\frac{1}{2048})$
1000	0000	0000	OV
0111	1111	1111	$-V_{REF}(\frac{1}{2048})$
0000	0000	0001	-V _{REF} ($\frac{2047}{2048}$)
0000	0000	0000	$-V_{REF} \left(\frac{2048}{2048} \right) = -V_{REF}$

NOTE: 1 LSB = $(V_{REF}) \left(\frac{1}{4096} \right)$

MIXIM

^{**}Depends on µP clock frequency.

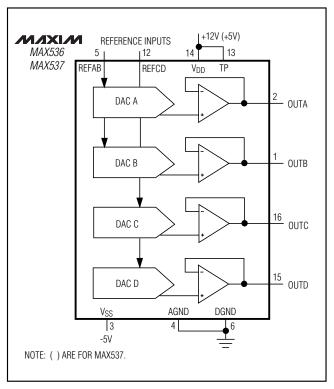


Figure 10. Unipolar Output Circuit

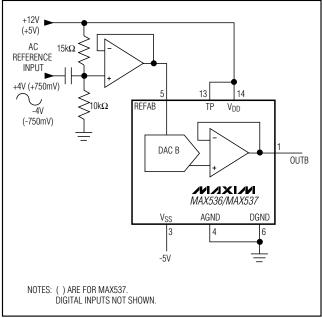


Figure 12. AC Reference Input Circuit

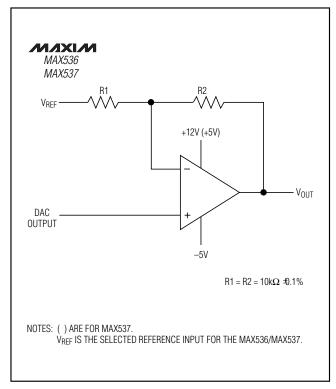


Figure 11. Bipolar Output Circuit

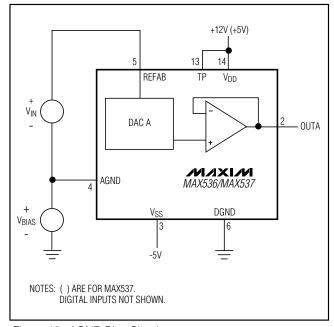


Figure 13. AGND Bias Circuit

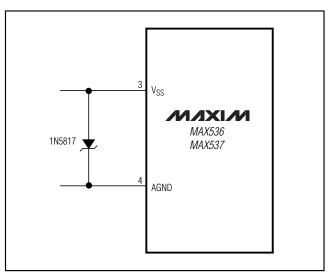


Figure 14. When V_{SS} and V_{DD} cannot be sequenced, tie a Schottky diode between V_{SS} and AGND.

Using an AC Reference

In applications where the reference has AC signal components, the MAX536/MAX537 have multiplying capability within the reference input range specifications. Figure 12 shows a technique for applying a sine-wave signal to the reference input where the AC signal is offset before being applied to REFAB/REFCD. The reference voltage must never be more negative than DGND.

The MAX536's total harmonic distortion plus noise (THD+N) is typically less than 0.012%, given a $5V_{P-P}$ signal swing and input frequencies up to 35kHz, or given a $2V_{P-P}$ swing and input frequencies up to 50kHz. The typical -3dB frequency is 700kHz as shown in the *Typical Operating Characteristics* graphs.

For the MAX537, with an input signal amplitude of 0.85mV_{P-P}, THD+N is typically less than 0.024% with a 5k Ω load in parallel with 100pF and input frequencies up to 100kHz, or with a 2k Ω load in parallel with 100pF and input frequencies up to 95kHz.

Offsetting AGND

AGND can be biased from DGND to the reference voltage to provide an arbitrary nonzero output voltage for a zero input code (Figure 13). The output voltage VOUTA is:

where V_{BIAS} is the positive offset voltage (with respect to DGND) applied to AGND, and N_B is the numeric value of the DAC's binary input code. Since AGND is common to all four DACs, all outputs will be offset by V_{BIAS} in the same manner. As the voltage at AGND increases, the DAC's resolution decreases because its full-scale voltage swing is effectively reduced. AGND should not be biased more negative than DGND.

Power-Supply Considerations

On power-up, Vss should come up first, VDD next, then REFAB or REFCD. If supply sequencing is not possible, tie an external Schottky diode between Vss and AGND as shown in Figure 14. On power-up, all input and DAC registers are cleared (set to zero code) and SDO is in Mode 0 (serial data is shifted out of SDO on the clock's rising edge).

For rated MAX536 performance, V_{DD} should be 4V higher than REFAB/REFCD and should be between 10.8V and 13.2V. When using the MAX537, V_{DD} should be at least 2.2V higher than REFAB/REFCD and should be between 4.75V and 5.5V. Bypass both V_{DD} and V_{SS} with a 4.7 μ F capacitor in parallel with a 0.1 μ F capacitor to AGND. Use short lead lengths and place the bypass capacitors as close to the supply pins as possible.

Grounding and Layout Considerations

Digital or AC transient signals between AGND and DGND can create noise at the analog outputs. Tie AGND and DGND together at the DAC, then tie this point to the highest quality ground available.

Good PCB ground layout minimizes crosstalk between DAC outputs, reference inputs, and digital inputs. Reduce crosstalk by keeping analog lines away from digital lines. Wire-wrapped boards are not recommended.

Ordering Information (continued)

PART	TEMP RANGE	PIN- PACKAGE	INL (LSB)
MAX537ACPE+	0°C to +70°C	16 PDIP	±0.5
MAX537BCPE+	0°C to +70°C	16 PDIP	±1
MAX537ACWE+	0°C to +70°C	16 Wide SO	±0.5
MAX537BCWE+	0°C to +70°C	16 Wide SO	±1
MAX537AEPE+	-40°C to +85°C	16 PDIP	±0.5
MAX537BEPE+	-40°C to +85°C	16 PDIP	±1
MAX537AEWE+	-40°C to +85°C	16 Wide SO	±0.5
MAX537BEWE+	-40°C to +85°C	16 Wide SO	±1

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

Package Information

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
16 PDIP	P16+9	<u>21-0043</u>	_
16 SO	W16+7	<u>21-0042</u>	<u>90-0107</u>

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	1/94	Initial release	
3	3/11	Removed dice and ceramic SB packages and changed voltage supply specifications	1–7, 13, 21, 22, 23

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